

ABSTRACT OF THE DISCLOSURE

**MOLECULAR BONDING OF MICROELECTRONIC COMPONENTS ON A
POLYMER FILM**

A method for direct molecular adhesion of an electronic compound (6) on a polymer (4) is described. The polymer (4) is coated with a bonding layer (5), for example silicon oxide, which enables the problems caused by the presence of hydrocarbons to be overcome. The method makes it possible to produce adhesive-free three-dimensional structures (10).

(Figure 2)